
Manual on

The Use of
Thermocouples
in Temperature
Measurement

Fourth Edition



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Foreword

The Manual on the Use of Thermocouples in Temperature Measurement was sponsored by ASTM Committee E20 on Temperature Measurement and was compiled by E20.94, the Publications Subcommittee. The editorial work was co-ordinated by R. M. Park, Marlin Manufacturing Corp. Helen M. Hoersch was the ASTM editor.

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ASTM would like to express its gratitude to the authors of the 1993 Edition of this publication. The original publication made a significant contribution to the technology, and, therefore, ASTM, in its goal to publish books of technical significance, called upon current experts in the field to revise and update this important publication to reflect those changes and advancements that have taken place over the past 10 years.

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